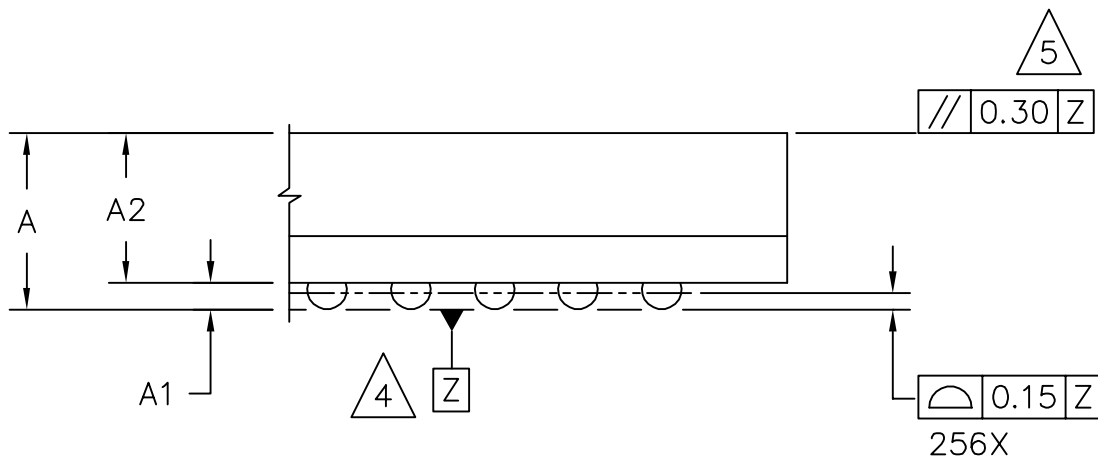


© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		<b>MECHANICAL OUTLINE</b>		PRINT VERSION NOT TO SCALE	
TITLE: 256 I/O STD MAP BGA, 17 X 17 PKG, 1.00 PITCH			DOCUMENT NO: 98ARH98219A		REV: A
			CASE NUMBER: 1216B-01		15 JUL 2005
			STANDARD: NON-JEDEC		



DETAIL K  
ROTATED 90° CLOCKWISE

DIM	MIN	MAX	NOTES
A	1.25	1.60	<p>1. DIMENSIONS ARE IN MILLIMETERS.</p> <p>2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.</p> <p>3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.</p> <p>4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.</p> <p>5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.</p>
A1	0.27	0.47	
A2	1.16	REF	
b	0.40	0.60	
D	17.00	BSC	
E	17.00	BSC	
e	1.00	BSC	
S	0.50	BSC	

© FREESCALE SEMICONDUCTOR, INC.  
ALL RIGHTS RESERVED.

**MECHANICAL OUTLINE**

PRINT VERSION NOT TO SCALE

TITLE:  
256 I/O STD MAP BGA,  
17 X 17 PKG, 1.00 PITCH

DOCUMENT NO: 98ARH98219A

REV: A

CASE NUMBER: 1216B-01

15 JUL 2005

STANDARD: NON-JEDEC